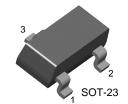


# **MMBT3646**

### **Switching Transistor**



1. Base 2. Emitter 3. Collector

### Absolute Maximum Ratings $T_C=25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Value	Units	
V <sub>CEO</sub>	Collector-Emitter Voltage	15	V	
V <sub>CES</sub>	Collector-Emitter Voltage	40	V	
V <sub>CBO</sub>	Collector-Base Voltage	40	V	
V <sub>EBO</sub>	Emitter-Base Voltage	5		
I <sub>C</sub>	Collector Current (DC) - Continuous	300	mA	
P <sub>D</sub>	Total Device Dissipation @ T <sub>A</sub> =25°C - Derate above 25°C	625 5	mW mW/°C	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	150	°C	

## Electrical Characteristics ${\rm T_{C}\text{=}}25^{\circ}{\rm C}$ unless otherwise noted

Symbol	Parameter	Min.	Тур.	Max.	Units
Off Characte	eristics				
V <sub>(BR)CES</sub>	Collector-Emitter Breakdown Voltage (I <sub>C</sub> = 100μAdc, V <sub>BE</sub> = 0)	40			V
V <sub>CEO(sus)</sub>	Collector-Emitter Sustaining Voltage (1) (I <sub>C</sub> = 10mAdc, I <sub>B</sub> = 0)	15			V
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage (I <sub>C</sub> = 100μAdc, I <sub>E</sub> = 0)	40			V
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage (I <sub>E</sub> = 100μAdc, I <sub>C</sub> = 0)	5			V
I <sub>CES</sub>	Collector Cut-off Current ( $V_{CE} = 20Vdc$ , $V_{BE} = 0$ ) ( $V_{CE} = 20Vdc$ , $V_{BE} = 0$ , $V_{AE} = 0$ )			0.5 3	μА
On Characte	ristics (1)				
h <sub>FE</sub>	DC Current Gain ( $I_C = 30$ mAdc, $V_{CE} = 0.4$ Vdc) ( $I_C = 100$ mAdc, $V_{CE} = 0.5$ Vdc) ( $I_C = 300$ mAdc, $V_{CE} = 1$ Vdc)			120	
V <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage ( $I_C$ = 30mAdc, $I_B$ = 3mAdc) ( $I_C$ = 100mAdc, $I_B$ = 10mAdc) ( $I_C$ = 300mAdc, $I_B$ = 30mAdc) ( $I_C$ = 30mA, $I_B$ = 3mA, $I_A$ =65°C)			0.2 0.28 0.5 0.3	V
V <sub>BE(sat)</sub>	Base-Emitter Saturation Voltage ( $I_C = 30 \text{mAdc}$ , $I_B = 3 \text{mAdc}$ ) ( $I_C = 100 \text{mAdc}$ , $I_B = 10 \text{mAdc}$ ) ( $I_C = 300 \text{mAdc}$ , $I_B = 30 \text{mAdc}$ )	0.73		0.95 1.2 1.7	V

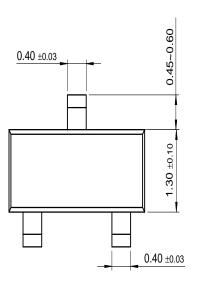
Symbol	Parameter			Тур.	Max.	Units
Small-Signal	Characteristics					
C <sub>obo</sub>	Output Capacitance (V <sub>CE</sub> = 5Vdc, I <sub>E</sub> = 0, f = 1MHz)				5	pF
C <sub>ibo</sub>	Input Capacitance (V <sub>EB</sub> = 0.5Vdc, I <sub>C</sub> = 0, f = 1MHz)				8	pF
Switching Ch	aracteristics					
t <sub>on</sub>	Turn-On Time	$V_{CC} = 10Vdc$ , $I_{C} = 300mAdc$ ,			18	ns
t <sub>d</sub>	Delay Time	$I_{B1} = 30 \text{mAdc}, V_{CE(off)} = 3 \text{V}$			10	ns
t <sub>r</sub>	Rise Time				15	ns
t <sub>off</sub>	Turn-Off Time	$V_{CC} = 10Vdc$ , $I_C = 300mAdc$ ,			28	ns
t <sub>f</sub>	Fall Time	$I_{B1} = I_{B2} = 30$ mAdc			15	ns
t <sub>s</sub>	Storge Time				20	ns

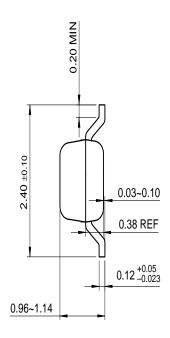
## **Thermal Characteristics**

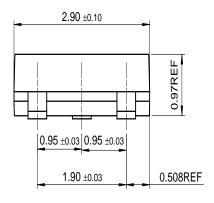
Symbol	Parameter	Min.	Тур.	Max.	Units
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient			200	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case			83.3	°C

# **Package Dimensions**

# **SOT-23**







Dimensions in Millimeters

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CoolFET™	FASTr™	MicroFET™	PowerTrench <sup>®</sup>	SuperSOT™-6
CROSSVOLT™	FRFET™	MicroPak™	QFET™	SuperSOT™-8
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EcoSPARK™	GTO™	MSX™	QT Optoelectronics™	TinyLogic™
E <sup>2</sup> CMOS™	HiSeC™	MSXPro™	Quiet Series™	TruTranslation™
EnSigna™	I <sup>2</sup> C <sup>TM</sup>	$OCX^{TM}$	RapidConfigure™	UHC™
Across the board.	. Around the world.™	OCXPro™	RapidConnect™	UltraFET <sup>®</sup>
The Power Franchise™		OPTOLOGIC <sup>®</sup>	SILENT SWITCHER®	$VCX^{TM}$
Programmable Ad	ctive Droop™	OPTOPLANAR™	SMART START™	

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